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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2400
Number of Logic Elements/Cells	10800
Total RAM Bits	163840
Number of I/O	316
Number of Gates	569952
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	432-LBGA Exposed Pad, Metal
Supplier Device Package	432-MBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv400e-6bg432c

Development System

Virtex-E FPGAs are supported by the Xilinx Foundation and Alliance Series CAE tools. The basic methodology for Virtex-E design consists of three interrelated steps: design entry, implementation, and verification. Industry-standard tools are used for design entry and simulation (for example, Synopsys FPGA Express), while Xilinx provides proprietary architecture-specific tools for implementation.

The Xilinx development system is integrated under the Xilinx Design Manager (XDM™) software, providing designers with a common user interface regardless of their choice of entry and verification tools. The XDM software simplifies the selection of implementation options with pull-down menus and on-line help.

Application programs ranging from schematic capture to Placement and Routing (PAR) can be accessed through the XDM software. The program command sequence is generated prior to execution, and stored for documentation.

Several advanced software features facilitate Virtex-E design. RPMs, for example, are schematic-based macros with relative location constraints to guide their placement. They help ensure optimal implementation of common functions.

For HDL design entry, the Xilinx FPGA Foundation development system provides interfaces to the following synthesis design environments.

- Synopsys (FPGA Compiler, FPGA Express)
- Exemplar (Spectrum)
- Synplicity (Synplify)

For schematic design entry, the Xilinx FPGA Foundation and Alliance development system provides interfaces to the following schematic-capture design environments.

- Mentor Graphics V8 (Design Architect, QuickSim II)
- Viewlogic Systems (Viewdraw)

Third-party vendors support many other environments.

A standard interface-file specification, Electronic Design Interchange Format (EDIF), simplifies file transfers into and out of the development system.

Virtex-E FPGAs are supported by a unified library of standard functions. This library contains over 400 primitives and macros, ranging from 2-input AND gates to 16-bit accumulators, and includes arithmetic functions, comparators, counters, data registers, decoders, encoders, I/O functions, latches, Boolean functions, multiplexers, shift registers, and barrel shifters.

The “soft macro” portion of the library contains detailed descriptions of common logic functions, but does not contain any partitioning or placement information. The performance of these macros depends, therefore, on the partitioning and placement obtained during implementation.

RPMs, on the other hand, do contain predetermined partitioning and placement information that permits optimal implementation of these functions. Users can create their own library of soft macros or RPMs based on the macros and primitives in the standard library.

The design environment supports hierarchical design entry, with high-level schematics that comprise major functional blocks, while lower-level schematics define the logic in these blocks. These hierarchical design elements are automatically combined by the implementation tools. Different design entry tools can be combined within a hierarchical design, thus allowing the most convenient entry method to be used for each portion of the design.

Design Implementation

The place-and-route tools (PAR) automatically provide the implementation flow described in this section. The partitioner takes the EDIF net list for the design and maps the logic into the architectural resources of the FPGA (CLBs and IOBs, for example). The placer then determines the best locations for these blocks based on their interconnections and the desired performance. Finally, the router interconnects the blocks.

The PAR algorithms support fully automatic implementation of most designs. For demanding applications, however, the user can exercise various degrees of control over the process. User partitioning, placement, and routing information is optionally specified during the design-entry process. The implementation of highly structured designs can benefit greatly from basic floor planning.

The implementation software incorporates Timing Wizard® timing-driven placement and routing. Designers specify timing requirements along entire paths during design entry. The timing path analysis routines in PAR then recognize these user-specified requirements and accommodate them.

Timing requirements are entered on a schematic in a form directly relating to the system requirements, such as the targeted clock frequency, or the maximum allowable delay between two registers. In this way, the overall performance of the system along entire signal paths is automatically tailored to user-generated specifications. Specific timing information for individual nets is unnecessary.

Design Verification

In addition to conventional software simulation, FPGA users can use in-circuit debugging techniques. Because Xilinx devices are infinitely reprogrammable, designs can be verified in real time without the need for extensive sets of software simulation vectors.

The development system supports both software simulation and in-circuit debugging techniques. For simulation, the system extracts the post-layout timing information from the design database, and back-annotates this information into the net list for use by the simulator. Alternatively, the user can verify timing-critical portions of the design using the TRCE® static timing analyzer.

Table 9 lists the total number of bits required to configure each device.

Table 9: **Virtex-E Bitstream Lengths**

Device	# of Configuration Bits
XCV50E	630,048
XCV100E	863,840
XCV200E	1,442,016
XCV300E	1, 875,648
XCV400E	2,693,440
XCV600E	3,961,632
XCV1000E	6,587,520
XCV1600E	8,308,992
XCV2000E	10,159,648
XCV2600E	12,922,336
XCV3200E	16,283,712

Slave-Serial Mode

In slave-serial mode, the FPGA receives configuration data in bit-serial form from a serial PROM or other source of serial configuration data. The serial bitstream must be set up at the DIN input pin a short time before each rising edge of an externally generated CCLK.

For more detailed information on serial PROMs, see the PROM data sheet at **http://www.xilinx.com/bvdocs/publications/ds026.pdf**.

Multiple FPGAs can be daisy-chained for configuration from a single source. After a particular FPGA has been configured, the data for the next device is routed to the DOUT pin. The maximum capacity for a single LOUT/DOUT write is 2^{20}-1 (1,048,575) 32-bit words, or 33,554,4000 bits. The data on the DOUT pin changes on the rising edge of CCLK.

The change of DOUT on the rising edge of CCLK differs from previous families, but does not cause a problem for mixed configuration chains. This change was made to improve serial configuration rates for Virtex and Virtex-E only chains.

Figure 13 shows a full master/slave system. A Virtex-E device in slave-serial mode should be connected as shown in the right-most device.

Slave-serial mode is selected by applying <111> or <011> to the mode pins (M2, M1, M0). A weak pull-up on the mode pins makes slave serial the default mode if the pins are left unconnected. However, it is recommended to drive the configuration mode pins externally. Figure 14 shows slave-serial mode programming switching characteristics.

Table 10 provides more detail about the characteristics shown in Figure 14. Configuration must be delayed until the $\overline{\text{INIT}}$ pins of all daisy-chained FPGAs are High.

Table 10: **Master/Slave Serial Mode Programming Switching**

	Description	Figure References	Symbol	Values	Units
CCLK	DIN setup/hold, slave mode	1/2	T_{DCC}/T_{CCD}	5.0 / 0.0	ns, min
	DIN setup/hold, master mode	1/2	T_{DSCK}/T_{CKDS}	5.0 / 0.0	ns, min
	DOUT	3	T_{CCO}	12.0	ns, max
	High time	4	T_{CCH}	5.0	ns, min
	Low time	5	T_{CCL}	5.0	ns, min
	Maximum Frequency		F_{CC}	66	MHz, max
	Frequency Tolerance, master mode with respect to nominal			+45% –30%	

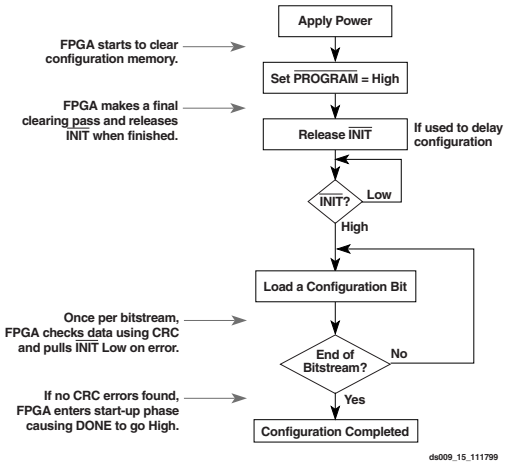


Figure 15: **Serial Configuration Flowchart**

Figure 16 shows the timing of master-serial configuration. Master-serial mode is selected by a <000> or <100> on the mode pins (M2, M1, M0). Table 10 shows the timing information for Figure 16.

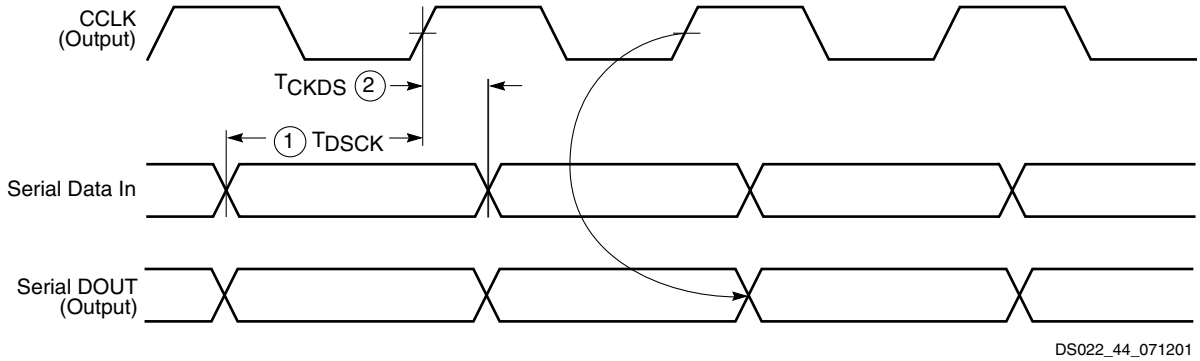


Figure 16: **Master-Serial Mode Programming Switching Characteristics**

At power-up, V_{CC} must rise from 1.0 V to V_{CC} Min in less than 50 ms, otherwise delay configuration by pulling $\overline{\text{PROGRAM}}$ Low until V_{CC} is valid.

SelectMAP Mode

The SelectMAP mode is the fastest configuration option. Byte-wide data is written into the FPGA with a BUSY flag controlling the flow of data.

An external data source provides a byte stream, CCLK, a Chip Select ($\overline{\text{CS}}$) signal and a Write signal ($\overline{\text{WRITE}}$). If BUSY is asserted (High) by the FPGA, the data must be held until BUSY goes Low.

Data can also be read using the SelectMAP mode. If $\overline{\text{WRITE}}$ is not asserted, configuration data is read out of the FPGA as part of a readback operation.

After configuration, the pins of the SelectMAP port can be used as additional user I/O. Alternatively, the port can be retained to permit high-speed 8-bit readback.

Retention of the SelectMAP port is selectable on a design-by-design basis when the bitstream is generated. If retention is selected, PROHIBIT constraints are required to prevent the SelectMAP-port pins from being used as user I/O.

Multiple Virtex-E FPGAs can be configured using the SelectMAP mode, and be made to start-up simultaneously. To configure multiple devices in this way, wire the individual CCLK, Data, $\overline{\text{WRITE}}$, and BUSY pins of all the devices in parallel. The individual devices are loaded separately by asserting the $\overline{\text{CS}}$ pin of each device in turn and writing the appropriate data. See Table 11 for SelectMAP Write Timing Characteristics.

Write

Write operations send packets of configuration data into the FPGA. The sequence of operations for a multi-cycle write operation is shown below. Note that a configuration packet can be split into many such sequences. The packet does not have to complete within one assertion of $\overline{\text{CS}}$, illustrated in Figure 17.

1. Assert $\overline{\text{WRITE}}$ and $\overline{\text{CS}}$ Low. Note that when $\overline{\text{CS}}$ is asserted on successive CCLKs, $\overline{\text{WRITE}}$ must remain either asserted or de-asserted. Otherwise, an abort is initiated, as described below.
2. Drive data onto D[7:0]. Note that to avoid contention, the data source should not be enabled while $\overline{\text{CS}}$ is Low and $\overline{\text{WRITE}}$ is High. Similarly, while $\overline{\text{WRITE}}$ is High, no more that one $\overline{\text{CS}}$ should be asserted.

Configuration through the TAP uses the CFG_IN instruction. This instruction allows data input on TDI to be converted into data packets for the internal configuration bus.

The following steps are required to configure the FPGA through the Boundary Scan port (when using TCK as a start-up clock).

1. Load the CFG_IN instruction into the Boundary Scan instruction register (IR).
2. Enter the Shift-DR (SDR) state.
3. Shift a configuration bitstream into TDI.
4. Return to Run-Test-Idle (RTI).
5. Load the JSTART instruction into IR.
6. Enter the SDR state.
7. Clock TCK through the startup sequence.
8. Return to RTI.

Configuration and readback via the TAP is always available. The Boundary Scan mode is selected by a <101> or <001> on the mode pins (M2, M1, M0). For details on TAP characteristics, refer to XAPP139.

Configuration Sequence

The configuration of Virtex-E devices is a three-phase process. First, the configuration memory is cleared. Next, configuration data is loaded into the memory, and finally, the logic is activated by a start-up process.

Configuration is automatically initiated on power-up unless it is delayed by the user, as described below. The configuration process can also be initiated by asserting $\overline{\text{PROGRAM}}$. The end of the memory-clearing phase is signalled by $\overline{\text{INIT}}$ going High, and the completion of the entire process is signalled by DONE going High.

The power-up timing of configuration signals is shown in Figure 20.

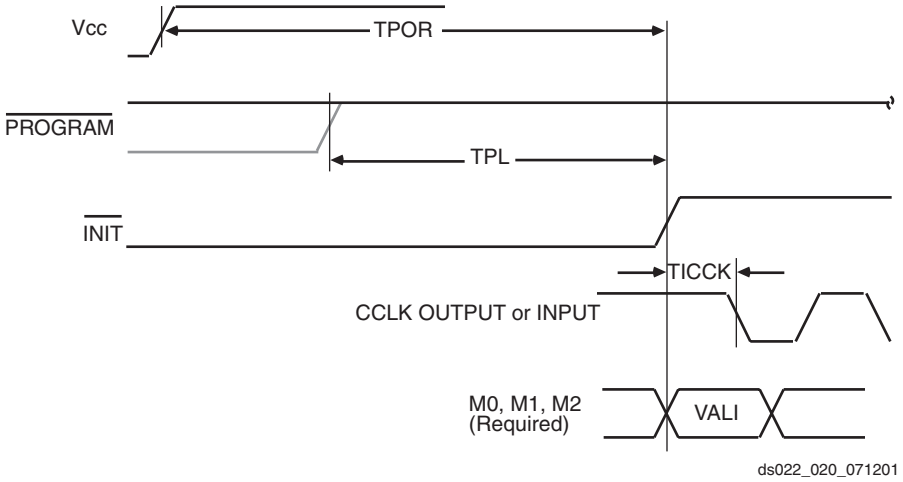


Figure 20: **Power-Up Timing Configuration Signals**

The corresponding timing characteristics are listed in Table 12.

Table 12: **Power-up Timing Characteristics**

Description	Symbol	Value	Units
Power-on Reset[1]	T_{POR}	2.0	ms, max
Program Latency	T_{PL}	100.0	µs, max
CCLK (output) Delay	T_{ICCK}	0.5	µs, min
		4.0	µs, max
Program Pulse Width	$T_{PROGRAM}$	300	ns, min

Notes:
1. T_{POR} delay is the initialization time required after V_{CCINT} and V_{CCO} in Bank 2 reach the recommended operating voltage.

Delaying Configuration

$\overline{\text{INIT}}$ can be held Low using an open-drain driver. An open-drain is required since $\overline{\text{INIT}}$ is a bidirectional open-drain pin that is held Low by the FPGA while the configuration memory is being cleared. Extending the time that the pin is Low causes the configuration sequencer to wait. Thus, configuration is delayed by preventing entry into the phase where data is loaded.

Start-Up Sequence

The default Start-up sequence is that one CCLK cycle after DONE goes High, the global 3-state signal (GTS) is released. This permits device outputs to turn on as necessary.

One CCLK cycle later, the Global Set/Reset (GSR) and Global Write Enable (GWE) signals are released. This permits

indicating that the block SelectRAM+ memory is now disabled. The DO bus retains the last value.

Dual Port Timing

Figure 34 shows a timing diagram for a true dual-port read/write block SelectRAM+ memory. The clock on port A has a longer period than the clock on Port B. The timing parameter T_{BCCS}, (clock-to-clock set-up) is shown on this diagram. The parameter, T_{BCCS} is violated once in the diagram. All other timing parameters are identical to the single port version shown in Figure 33.

T_{BCCS} is only of importance when the address of both ports are the same and at least one port is performing a write operation. When the clock-to-clock set-up parameter is violated for a WRITE-WRITE condition, the contents of the memory at that location are invalid. When the clock-to-clock set-up parameter is violated for a WRITE-READ condition, the contents of the memory are correct, but the read port has invalid data.

At the first rising edge of the CLKA, memory location 0x00 is to be written with the value 0xAAAA and is mirrored on the DOA bus. The last operation of Port B was a read to the same memory location 0x00. The DOB bus of Port B does not change with the new value on Port A, and retains the last read value. A short time later, Port B executes another read to memory location 0x00, and the DOB bus now reflects the new memory value written by Port A.

At the second rising edge of CLKA, memory location 0x7E is written with the value 0x9999 and is mirrored on the DOA bus. Port B then executes a read operation to the same memory location without violating the T_{BCCS} parameter and the DOB reflects the new memory values written by Port A.

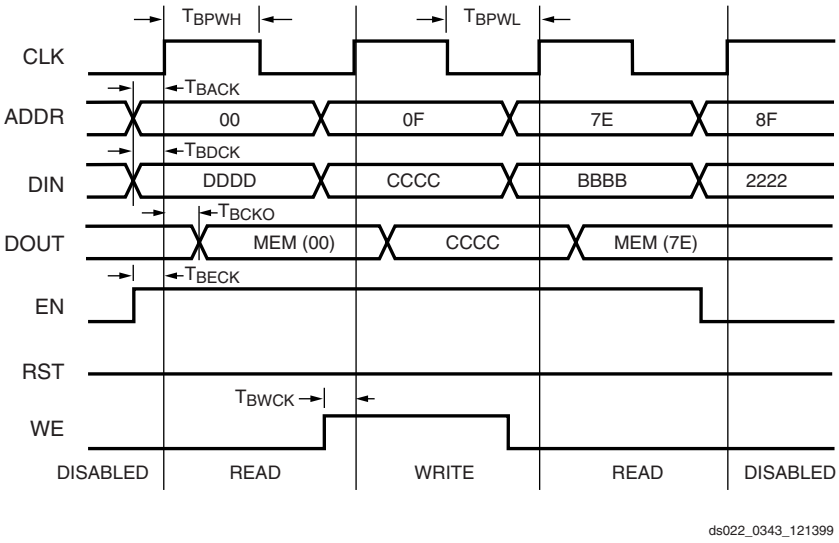


Figure 33: **Timing Diagram for Single Port Block SelectRAM+ Memory**

IOB Flip-Flop/Latch Property

The Virtex-E series I/O Block (IOB) includes an optional register on the input path, an optional register on the output path, and an optional register on the 3-state control pin. The design implementation software automatically takes advantage of these registers when the following option for the Map program is specified.

map –pr b <filename>

Alternatively, the IOB = TRUE property can be placed on a register to force the mapper to place the register in an IOB.

Location Constraints

Specify the location of each SelectI/O symbol with the location constraint LOC attached to the SelectI/O symbol. The external port identifier indicates the value of the location constrain. The format of the port identifier depends on the package chosen for the specific design.

The LOC properties use the following form:

LOC=A42

LOC=P37

Output Slew Rate Property

As mentioned above, a variety of symbol names provide the option of choosing the desired slew rate for the output buffers. In the case of the LVTTL output buffers (OBUF, OBUFT, and IOBUF), slew rate control can be alternatively programed with the SLEW= property. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals. The SLEW= property has one of the two following values.

SLEW=SLOW

SLEW=FAST

Output Drive Strength Property

The desired output drive strength can be additionally specified by choosing the appropriate library symbol. The Xilinx library also provides an alternative method for specifying this feature. For the LVTTL output buffers (OBUF, OBUFT, and IOBUF, the desired drive strength can be specified with the DRIVE= property. This property could have one of the following seven values.

DRIVE=2
DRIVE=4
DRIVE=6
DRIVE=8
DRIVE=12 (Default)
DRIVE=16
DRIVE=24

Design Considerations

Reference Voltage (V_{REF}) Pins

Low-voltage I/O standards with a differential amplifier input buffer require an input reference voltage (V_{REF}). Provide the V_{REF} as an external signal to the device.

The voltage reference signal is “banked” within the device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

Within each V_{REF} bank, any input buffers that require a V_{REF} signal must be of the same type. Output buffers of any type and input buffers can be placed without requiring a reference voltage within the same V_{REF} bank.

Output Drive Source Voltage (V_{CCO}) Pins

Many of the low voltage I/O standards supported by SelectI/O devices require a different output drive source voltage (V_{CCO}). As a result each device can often have to support multiple output drive source voltages.

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS package supports four V_{CCO} banks.

Output buffers within a given V_{CCO} bank must share the same output drive source voltage. Input buffers for LVTTL, LVCMOS2, LVCMOS18, PCI33_3, and PCI 66_3 use the V_{CCO} voltage for Input V_{CCO} voltage.

Transmission Line Effects

The delay of an electrical signal along a wire is dominated by the rise and fall times when the signal travels a short distance. Transmission line delays vary with inductance and capacitance, but a well-designed board can experience delays of approximately 180 ps per inch.

Transmission line effects, or reflections, typically start at 1.5" for fast (1.5 ns) rise and fall times. Poor (or non-existent) termination or changes in the transmission line impedance cause these reflections and can cause additional delay in longer traces. As system speeds continue to increase, the effect of I/O delays can become a limiting factor and therefore transmission line termination becomes increasingly more important.

Termination Techniques

A variety of termination techniques reduce the impact of transmission line effects.

The following are output termination techniques:

- None
- Series
- Parallel (Shunt)
- Series and Parallel (Series-Shunt)

HSTL

A sample circuit illustrating a valid termination technique for HSTL_I appears in Figure 46. A sample circuit illustrating a valid termination technique for HSTL_III appears in Figure 47.

Table 25: **HSTL Class I Voltage Specification**

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF}	0.68	0.75	0.90
V_{TT}	-	$V_{CCO} \times 0.5$	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}			0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL} at V_{OL} (mA)	8	-	-

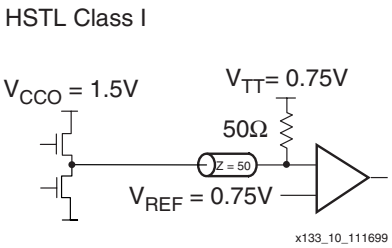


Figure 46: **Terminated HSTL Class I**

Table 26: **HSTL Class III Voltage Specification**

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF} (1)	-	0.90	-
V_{TT}	-	V_{CCO}	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL} at V_{OL} (mA)	24	-	-

Note: Per EIA/JESD8-6, "The value of V_{REF} is to be selected by the user to provide optimum noise margin in the use conditions specified by the user."

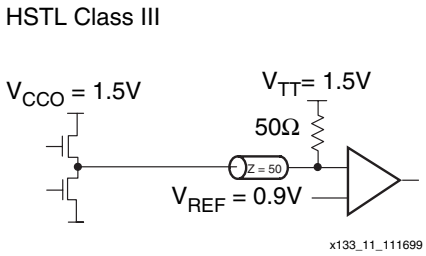


Figure 47: **Terminated HSTL Class III**

A sample circuit illustrating a valid termination technique for HSTL_IV appears in Figure 48.

Table 27: **HSTL Class IV Voltage Specification**

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF}	-	0.90	-
V_{TT}	-	V_{CCO}	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL} at V_{OL} (mA)	48	-	-

Note: Per EIA/JESD8-6, "The value of V_{REF} is to be selected by the user to provide optimum noise margin in the use conditions specified by the user.

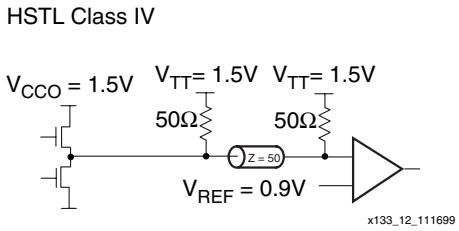


Figure 48: **Terminated HSTL Class IV**

LVTTL

LVTTL requires no termination. DC voltage specifications appears in Table 34.

Table 34: **LVTTL Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	2.0	-	3.6
V_{IL}	–0.5	-	0.8
V_{OH}	2.4	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–24	-	-
I_{OL} at V_{OL} (mA)	24	-	-

Notes:
1. Note: V_{OL} and V_{OH} for lower drive currents sample tested.

LVCMOS2

LVCMOS2 requires no termination. DC voltage specifications appear in Table 35.

Table 35: **LVCMOS2 Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.3	2.5	2.7
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	1.7	-	3.6
V_{IL}	–0.5	-	0.7
V_{OH}	1.9	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–12	-	-
I_{OL} at V_{OL} (mA)	12	-	-

LVCMOS18

LVCMOS18 does not require termination. Table 36 lists DC voltage specifications.

Table 36: **LVCMOS18 Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	1.70	1.80	1.90
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	0.65 x V_{CCO}	-	1.95
V_{IL}	– 0.5	-	0.2 x V_{CCO}
V_{OH}	V_{CCO} – 0.4	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL} at V_{OL} (mA)	8	-	-

AGP-2X

The specification for the AGP-2X standard does not document a recommended termination technique. DC voltage specifications appear in Table 37.

Table 37: **AGP-2X Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
$V_{REF} = N \times V_{CCO}$ (1)	1.17	1.32	1.48
V_{TT}	-	-	-
$V_{IH} = V_{REF} + 0.2$	1.37	1.52	-
$V_{IL} = V_{REF} – 0.2$	-	1.12	1.28
$V_{OH} = 0.9 \times V_{CCO}$	2.7	3.0	-
$V_{OL} = 0.1 \times V_{CCO}$	-	0.33	0.36
I_{OH} at V_{OH} (mA)	Note 2	-	-
I_{OL} at V_{OL} (mA)	Note 2	-	-

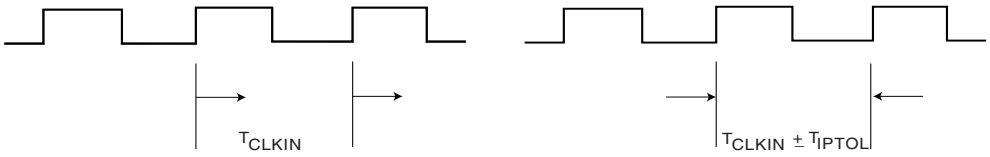
Notes:
1. N must be greater than or equal to 0.39 and less than or equal to 0.41.
2. Tested according to the relevant specification.

DLL Timing Parameters

All devices are 100 percent functionally tested. Because of the difficulty in directly measuring many internal timing parameters, those parameters are derived from benchmark timing patterns. The following guidelines reflect worst-case values across the recommended operating conditions.

Description	Symbol	F_{CLKIN}	Speed Grade						Units
			-8		-7		-6		
			Min	Max	Min	Max	Min	Max	
Input Clock Frequency (CLKDLLHF)	FCLKINHF		60	350	60	320	60	275	MHz
Input Clock Frequency (CLKDLL)	FCLKINLF		25	160	25	160	25	135	MHz
Input Clock Low/High Pulse Width	T_{DLLPW}	≥2□5 MHz	5.0		5.0		5.0		ns
		≥□50 MHz	3.0		3.0		3.0		ns
		≥100 MHz	2.4		2.4		2.4		ns
		≥□150 MHz	2.0		2.0		2.0		ns
		≥□200 MHz	1.8		1.8		1.8		ns
		≥□250 MHz	1.5		1.5		1.5		ns
		≥□300 MHz	1.3		1.3		NA		ns

Period Tolerance: the allowed input clock period change in nanoseconds.



Output Jitter: the difference between an ideal reference clock edge and the actual design.

Phase Offset and Maximum Phase Difference

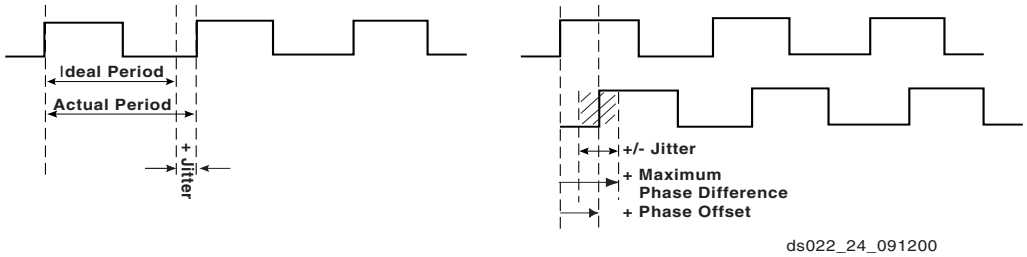


Figure 4: **DLL Timing Waveforms**

Table 5: **CS144 Differential Pin Pair Summary XCV50E, XCV100E, XCV200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
18	5	N8	M6	NA	IO_LVDS_DLL
19	5	K6	N5	√	-
20	5	K5	N4	√	VREF
21	5	N3	M3	√	-
22	6	K3	L1	√	-
23	6	J2	J3	1	VREF
24	6	H3	H4	√	-
25	6	H1	H2	1	VREF
26	7	F2	G1	NA	-
27	7	E1	F4	1	VREF
28	7	E3	E2	√	-
29	7	D2	D1	1	VREF

Note 1: AO in the XCV50E

PQ240 Plastic Quad Flat-Pack Packages

XCV50E, XCV100E, XCV200E, XCV300E and XCV400E devices in PQ240 Plastic Flat-pack packages have footprint compatibility. Pins labeled I0_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 6, see Table 7 for Differential Pair information.

Table 6: **PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pin #	Pin Description	Bank
P238	IO	0
P237	IO_L0N_Y	0
P236[2]	IO_VREF_L0P_Y	0
P235	IO_L1N_YY	0
P234	IO_L1P_YY	0
P231	IO_VREF	0
P230	IO	0
P229[1]	IO_VREF_L2N_YY	0
P228	IO_L2P_YY	0
P224	IO_L3N_YY	0
P223	IO_L3P_YY	0

Table 6: **PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pin #	Pin Description	Bank
P222	IO	0
P221	IO_L4N_Y	0
P220	IO_L4P_Y	0
P218	IO_VREF_L5N_Y	0
P217	IO_L5P_Y	0
P216[3]	IO_VREF	0
P215	IO_LVDS_DLL_L6N	0
P213	GCK3	0
P210	GCK2	1
P209	IO_LVDS_DLL_L6P	1
P208[3]	IO_VREF	1
P206	IO_L7N_Y	1
P205	IO_VREF_L7P_Y	1
P203	IO_L8N_Y	1
P202	IO_L8P_Y	1
P201	IO	1
P200	IO_L9N_YY	1
P199	IO_L9P_YY	1
P195	IO_L10N_YY	1
P194[1]	IO_VREF_L10P_YY	1
P193	IO	1
P192	IO_L11N_YY	1
P191	IO_VREF_L11P_YY	1
P189	IO_L12N_YY	1
P188	IO_L12P_YY	1
P187[2]	IO_VREF_L13N_Y	1
P186	IO_L13P_Y	1
P185	IO_WRITE_L14N_YY	1
P184	IO_CS_L14P_YY	1
P178	IO_DOUT_BUSY_L15P_YY	2
P177	IO_DIN_D0_L15N_YY	2
P175[2]	IO_VREF	2
P174	IO_L16P_Y	2

Table 6: **PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pin #	Pin Description	Bank
P74	IO_L43P_YY	5
P73[1]	IO_VREF_L43N_YY	5
P72	IO	5
P71	IO_L44P_YY	5
P70	IO_VREF_L44N_YY	5
P68	IO_L45P_YY	5
P67	IO_L45N_YY	5
P66[2]	IO_VREF_L46P_Y	5
P65	IO_L46N_Y	5
P64	IO_L47P_YY	5
P63	IO_L47N_YY	5
P57	IO_L48N_YY	6
P56	IO_L48P_YY	6
P54[2]	IO_VREF	6
P53	IO_L49N_Y	6
P52	IO_L49P_Y	6
P50	IO_VREF_L50N_Y	6
P49	IO_L50P_Y	6
P48	IO	6
P47[1]	IO_VREF_L51N_Y	6
P46	IO_L51P_Y	6
P42	IO_L52N_YY	6
P41	IO_L52P_YY	6
P40	IO	6
P39	IO_L53N_Y	6
P38	IO_L53P_Y	6
P36	IO_VREF_L54N_Y	6
P35	IO_L54P_Y	6
P34	IO_L55N_Y	6
P33[3]	IO_VREF_L55P_Y	6
P31	IO	6
P28	IO_L56N_YY	7
P27	IO_L56P_YY	7

Table 6: **PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pin #	Pin Description	Bank
P26[3]	IO_VREF	7
P24	IO_L57N_Y	7
P23	IO_VREF_L57P_Y	7
P21	IO_L58N_Y	7
P20	IO_L58P_Y	7
P19	IO	7
P18	IO_L59N_YY	7
P17	IO_L59P_YY	7
P13	IO_L60N_Y	7
P12[1]	IO_VREF_L60P_Y	7
P11	IO	7
P10	IO_L61N_Y	7
P9	IO_VREF_L61P_Y	7
P7	IO_L62N_Y	7
P6	IO_L62P_Y	7
P5[2]	IO_VREF_L63N_Y	7
P4	IO_L63P_Y	7
P3	IO	7
P179	CCLK	2
P120	DONE	3
P60	M0	NA
P58	M1	NA
P62	M2	NA
P122	PROGRAM	NA
P183	TDI	NA
P239	TCK	NA
P181	TDO	2
P2	TMS	NA
P225	VCCINT	NA
P214	VCCINT	NA
P198	VCCINT	NA
P164	VCCINT	NA
P148	VCCINT	NA

Table 7: **PQ240 Differential Pin Pair Summary XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
48	6	P56	P57	√	-
49	6	P52	P53	2	-
50	6	P49	P50	3	VREF
51	6	P46	P47	4	VREF
52	6	P41	P42	√	-
53	6	P38	P39	2	-
54	6	P35	P36	4	VREF
55	6	P33	P34	5	VREF
56	7	P27	P28	√	-
57	7	P23	P24	4	VREF
58	7	P20	P21	2	-
59	7	P17	P18	√	-
60	7	P12	P13	4	VREF
61	7	P9	P10	3	VREF
62	7	P6	P7	2	-
63	7	P4	P5	6	VREF

Notes:
1. AO in the XCV50E.
2. AO in the XCV50E, 100E, 200E, 300E.
3. AO in the XCV50E, 200E, 300E, 400E.
4. AO in the XCV50E, 300E, 400E.
5. AO in the XCV100E, 200E, 400E.
6. AO in the XCV100E, 400E.
7. AO in the XCV50E, 200E, 400E.
8. AO in the XCV100E.

HQ240 High-Heat Quad Flat-Pack Packages

XCV600E and XCV1000E devices in High-heat dissipation Quad Flat-pack packages have footprint compatibility. Pins labeled I0_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 8, see Table 9 for Differential Pair information.

Table 8: **HQ240 — XCV600E, XCV1000E**

Pin #	Pin Description	Bank
P240	VCCO	7
P239	TCK	NA
P238	IO	0
P237	IO_L0N	0
P236	IO_VREF_L0P	0
P235	IO_L1N_YY	0
P234	IO_L1P_YY	0
P233	GND	NA
P232	VCCO	0
P231	IO_VREF	0
P230	IO_VREF	0
P229	IO_VREF_L2N_YY	0
P228	IO_L2P_YY	0
P227	GND	NA
P226	VCCO	0
P225	VCCINT	NA
P224	IO_L3N_YY	0
P223	IO_L3P_YY	0
P222	IO_VREF	0[1]
P221	IO_L4N_Y	0
P220	IO_L4P_Y	0
P219	GND	NA
P218	IO_VREF_L5N_Y	0
P217	IO_L5P_Y	0
P216	IO_VREF	0
P215	IO_LVDS_DLL_L6N	0
P214	VCCINT	NA
P213	GCK3	0
P212	VCCO	0
P211	GND	NA

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
0	IO_L12N_YY	A20
0	IO_L12P_YY	D19
0	IO_VREF_L13N_YY	B19
0	IO_L13P_YY	A19
0	IO_L14N_Y	B18
0	IO_L14P_Y	D18
0	IO_VREF_L15N_Y	C18[2]
0	IO_L15P_Y	B17
0	IO_LVDS_DLL_L16N	C17
1	GCK2	A16
1	IO	A12
1	IO	B9
1	IO	B11
1	IO	C16
1	IO	D9
1	IO_LVDS_DLL_L16P	B16
1	IO_L17N_Y	A15
1	IO_VREF_L17P_Y	B15[2]
1	IO_L18N_Y	C15
1	IO_L18P_Y	D15
1	IO_L19N_YY	B14
1	IO_VREF_L19P_YY	A13
1	IO_L20N_YY	B13
1	IO_L20P_YY	D14
1	IO_L21N_YY	C13
1	IO_L21P_YY	B12
1	IO_L22N_YY	D13
1	IO_L22P_YY	C12
1	IO_L23N_YY	D12
1	IO_L23P_YY	C11
1	IO_L24N_YY	B10
1	IO_VREF_L24P_YY	C10
1	IO_L25N_Y	C9
1	IO_VREF_L25P_Y	D10[1]
1	IO_L26N_Y	A8

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
1	IO_L26P_Y	B8
1	IO_L27N_YY	C8
1	IO_VREF_L27P_YY	B7
1	IO_L28N_YY	D8
1	IO_L28P_YY	A6
1	IO_L29N_Y	B6
1	IO_L29P_Y	D7
1	IO_L30N_YY	A5
1	IO_VREF_L30P_YY	C6
1	IO_L31N_YY	B5
1	IO_L31P_YY	D6
1	IO_L32N_Y	A4
1	IO_L32P_Y	C5
1	IO_WRITE_L33N_YY	B4
1	IO_CS_L33P_YY	D5
2	IO	H4
2	IO	J3
2	IO	L3
2	IO	M1
2	IO	R2
2	IO_DOUT_BUSY_L34P_YY	D3
2	IO_DIN_D0_L34N_YY	C2
2	IO_L35P	D2
2	IO_L35N	E4
2	IO_L36P_Y	D1
2	IO_L36N_Y	E3
2	IO_VREF_L37P_Y	E2
2	IO_L37N_Y	F4
2	IO_L38P	E1
2	IO_L38N	F3
2	IO_L39P_Y	F2
2	IO_L39N_Y	G4
2	IO_VREF_L40P_YY	G3
2	IO_L40N_YY	G2
2	IO_L41P_Y	H3

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
7	IO_L132P_Y	G28
7	IO_L133N	E31
7	IO_L133P	E30
7	IO_L134N_Y	F29
7	IO_VREF_L134P_Y	F28
7	IO_L135N_Y	D31
7	IO_L135P_Y	D30
7	IO_L136N	E29
7	IO_L136P	E28
2	CCLK	D4
3	DONE	AH4
NA	DXN	AH27
NA	DXP	AK29
NA	M0	AH28
NA	M1	AH29
NA	M2	AJ28
NA	PROGRAM	AH3
NA	TCK	D28
NA	TDI	B3
2	TDO	C4
NA	TMS	D29
NA	VCCINT	A10
NA	VCCINT	A17
NA	VCCINT	B23
NA	VCCINT	B26
NA	VCCINT	C7
NA	VCCINT	C14
NA	VCCINT	C19
NA	VCCINT	F1
NA	VCCINT	F30
NA	VCCINT	K3
NA	VCCINT	K29
NA	VCCINT	N2
NA	VCCINT	N29

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	VCCINT	T1
NA	VCCINT	T29
NA	VCCINT	W2
NA	VCCINT	W31
NA	VCCINT	AB2
NA	VCCINT	AB30
NA	VCCINT	AE29
NA	VCCINT	AF1
NA	VCCINT	AH8
NA	VCCINT	AH24
NA	VCCINT	AJ10
NA	VCCINT	AJ16
NA	VCCINT	AK22
NA	VCCINT	AK13
NA	VCCINT	AK19
0	VCCO	A21
0	VCCO	C29
0	VCCO	D21
1	VCCO	A1
1	VCCO	A11
1	VCCO	D11
2	VCCO	C3
2	VCCO	L4
2	VCCO	L1
3	VCCO	AA1
3	VCCO	AA4
3	VCCO	AJ3
4	VCCO	AH11
4	VCCO	AL1
4	VCCO	AL11
5	VCCO	AH21
5	VCCO	AL21
5	VCCO	AJ29
6	VCCO	AA28
6	VCCO	AA31

Table 14: **BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin#	See Note
1	IO_L43N_Y	C5	
1	IO_VREF_L43P_Y	E7	3
1	IO_WRITE_L44N_YY	D6	
1	IO_CS_L44P_YY	A2	
2	IO	D3	
2	IO	F3	
2	IO	G1	
2	IO	J2	
2	IO_DOUT_BUSY_L45P_YY	D4	
2	IO_DIN_D0_L45N_YY	E4	
2	IO_L46P_Y	F5	
2	IO_VREF_L46N_Y	B3	3
2	IO_L47P_Y	F4	
2	IO_L47N_Y	C1	
2	IO_VREF_L48P_Y	G5	
2	IO_L48N_Y	E3	
2	IO_L49P_Y	D2	
2	IO_L49N_Y	G4	
2	IO_L50P_Y	H5	
2	IO_L50N_Y	E2	
2	IO_VREF_L51P_YY	H4	
2	IO_L51N_YY	G3	
2	IO_L52P_Y	J5	
2	IO_VREF_L52N_Y	F1	1
2	IO_L53P_Y	J4	
2	IO_L53N_Y	H3	
2	IO_VREF_L54P_Y	K5	4
2	IO_L54N_Y	H2	
2	IO_L55P_Y	J3	
2	IO_L55N_Y	K4	
2	IO_VREF_L56P_YY	L5	
2	IO_D1_L56N_YY	K3	
2	IO_D2_L57P_YY	L4	
2	IO_L57N_YY	K2	

Table 14: **BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin#	See Note
2	IO_L58P_Y	M5	
2	IO_L58N_Y	L3	
2	IO_L59P_Y	L1	
2	IO_L59N_Y	M4	
2	IO_VREF_L60P_Y	N5	3
2	IO_L60N_Y	M2	
2	IO_L61P_Y	N4	
2	IO_L61N_Y	N3	
2	IO_L62P_Y	N2	
2	IO_L62N_Y	P5	
2	IO_VREF_L63P_YY	P4	
2	IO_D3_L63N_YY	P3	
2	IO_L64P_Y	P2	
2	IO_L64N_Y	R5	
2	IO_L65P_Y	R4	
2	IO_L65N_Y	R3	
2	IO_VREF_L66P_Y	R1	
2	IO_L66N_Y	T4	
2	IO_L67P_Y	T5	
2	IO_VREF_L67N_Y	T3	2
2	IO_L68P_YY	T2	
2	IO_L68N_YY	U3	
3	IO	AE3	
3	IO	AF3	
3	IO	AH3	
3	IO	AK3	
3	IO_VREF_L69P_Y	U1	2
3	IO_L69N_Y	U2	
3	IO_L70P_Y	V2	
3	IO_VREF_L70N_Y	V4	
3	IO_L71P_Y	V5	
3	IO_L71N_Y	V3	
3	IO_L72P_Y	W1	
3	IO_L72N_Y	W3	

FG676 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs than can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 21: **FG676 Differential Pin Pair Summary XCV400E, XCV600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
3	0	E13	B13	NA	IO_DLL_L21N
2	1	C13	F14	NA	IO_DLL_L21P
1	5	AB13	AF13	NA	IO_DLL_L115N
0	4	AA14	AC14	NA	IO_DLL_L115P
IOLVDS Total Pairs: 183, Asynchronous Output Pairs: 97					
0	0	F7	C4	1	-
1	0	C5	G8	√	-
2	0	E7	D6	√	VREF
3	0	F8	A4	NA	-
4	0	D7	B5	NA	-
5	0	G9	E8	√	VREF
6	0	F9	A5	√	-
7	0	C7	D8	1	-
8	0	E9	B7	1	VREF
9	0	D9	A7	NA	-
10	0	G10	B8	NA	VREF
11	0	F10	C9	√	-
12	0	E10	A8	1	-
13	0	D10	G11	√	-
14	0	F11	B10	√	-
15	0	E11	C10	NA	-
16	0	D11	G12	√	-
17	0	F12	C11	√	VREF

Table 21: **FG676 Differential Pin Pair Summary XCV400E, XCV600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
18	0	E12	A11	√	-
19	0	C12	D12	1	-
20	0	H13	A12	1	VREF
21	1	F14	B13	NA	IO_LVDS_DLL
22	1	F13	E14	NA	-
23	1	A14	D14	1	VREF
24	1	H14	C14	1	-
25	1	C15	G14	√	-
26	1	D15	E15	√	VREF
27	1	F15	C16	√	-
28	1	D16	G15	-	-
29	1	A17	E16	√	-
30	1	E17	C17	√	-
31	1	D17	F16	1	-
32	1	C18	F17	√	-
33	1	G16	A18	√	VREF
34	1	G17	C19	√	-
35	1	B19	D18	1	VREF
36	1	E18	D19	1	-
37	1	B20	F18	√	-
38	1	C20	G19	√	VREF
39	1	E19	G18	√	-
40	1	D20	A21	√	-
41	1	C21	F19	√	VREF
42	1	E20	B22	√	-
43	1	D21	A23	2	-
44	1	E21	C22	√	CS
45	2	E23	F22	√	DIN, D0
46	2	E24	F20	√	-
47	2	G21	G22	2	-
48	2	F24	H20	1	VREF
49	2	E25	H21	1	-
50	2	F23	G23	√	-
51	2	H23	J20	√	VREF

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
3	IO_L97N	AA2
3	IO_L98P_YY	AC5
3	IO_L98N_YY	AB1
3	IO_D4_L99P_YY	AD3
3	IO_VREF_L99N_YY	AC1
3	IO_L100P_Y	AD1
3	IO_L100N_Y	AD4
3	IO_L101P	AD2
3	IO_L101N	AE3
3	IO_L102P_YY	AE1
3	IO_L102N_YY	AE4
3	IO_L103P_Y	AE2
3	IO_VREF_L103N_Y	AF3[1]
3	IO_L104P	AF4
3	IO_L104N	AF1
3	IO_L105P	AG3
3	IO_L105N	AF2
3	IO_L106P_Y	AG4
3	IO_L106N_Y	AG1
3	IO_L107P_YY	AH3
3	IO_D5_L107N_YY	AG2
3	IO_D6_L108P_YY	AH1
3	IO_VREF_L108N_YY	AJ2
3	IO_L109P	AH2
3	IO_L109N	AJ3
3	IO_L110P_YY	AJ1
3	IO_L110N_YY	AJ4
3	IO_L111P_YY	AK1
3	IO_VREF_L111N_YY	AK3
3	IO_L112P	AK2
3	IO_L112N	AK4
3	IO_L113P	AL1
3	IO_VREF_L113N	AL2[3]
3	IO_L114P_YY	AM1
3	IO_L114N_YY	AL3
3	IO_L115P_YY	AM2
3	IO_VREF_L115N_YY	AL4
3	IO_L116P_Y	AM3
3	IO_L116N_Y	AN1
3	IO_L117P	AM4
3	IO_L117N	AP1
3	IO_L118P_YY	AN2
3	IO_L118N_YY	AP2
3	IO_L119P_Y	AN3
3	IO_VREF_L119N_Y	AR1
3	IO_L120P	AN4
3	IO_L120N	AT1
3	IO_L121P	AR2
3	IO_VREF_L121N	AP4[1]
3	IO_L122P_Y	AT2
3	IO_L122N_Y	AR3
3	IO_D7_L123P_YY	AR4
3	IO_INIT_L123N_YY	AU2
4	GCK0	AW19
4	IO	AV3
4	IO_L124P_YY	AU4
4	IO_L124N_YY	AV5
4	IO_L125P_Y	AT6
4	IO_L125N_Y	AV4
4	IO_VREF_L126P_Y	AU6[1]
4	IO_L126N_Y	AW4
4	IO_L127P_YY	AT7
4	IO_L127N_YY	AW5
4	IO_VREF_L128P_YY	AU7
4	IO_L128N_YY	AV6
4	IO_L129P_Y	AT8
4	IO_L129N_Y	AW6
4	IO_L130P_Y	AU8
4	IO_L130N_Y	AV7
4	IO_L131P_YY	AT9
4	IO_L131N_YY	AW7

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
188	5	AA12	AJ12	√	VREF
189	5	AB12	AE11	√	-
190	5	AK12	Y13	2	-
191	5	AG11	AF11	2	-
192	5	AH11	AJ11	2	-
193	5	AE12	AG10	4	-
194	5	AD12	AK11	√	-
195	5	AJ10	AC12	√	VREF
196	5	AK10	AD11	4	-
197	5	AJ9	AE9	4	-
198	5	AH10	AF9	√	VREF
199	5	AH9	AK9	√	-
200	5	AF8	AB11	2	-
201	5	AC11	AG8	2	-
202	5	AK8	AF7	√	VREF
203	5	AG7	AK7	√	-
204	5	AJ7	AD10	1	-
205	5	AH6	AC10	1	-
206	5	AD9	AG6	√	VREF
207	5	AB10	AJ5	√	-
208	5	AD8	AK5	2	-
209	5	AC9	AJ4	2	VREF
210	5	AG5	AK4	2	-
211	5	AH5	AG3	4	-
212	6	AC6	AF3	√	-
213	6	AG2	AH2	NA	-
214	6	AE4	AB9	1	-
215	6	AH1	AE3	4	VREF
216	6	AD6	AB8	3	-
217	6	AA10	AG1	4	-
218	6	AD4	AA9	1	VREF
219	6	AD2	AD5	√	-
220	6	AF2	AD3	4	-
221	6	AA7	AA8	1	-

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
222	6	Y9	AF1	√	VREF
223	6	AC4	AB6	√	-
224	6	W8	AE1	2	-
225	6	AB4	Y8	4	-
226	6	W9	AB3	4	VREF
227	6	W10	AA5	4	-
228	6	V10	AB1	4	-
229	6	AC1	Y7	4	VREF
230	6	AA3	V11	NA	-
231	6	U10	AA2	4	-
232	6	AA6	W7	1	-
233	6	Y4	Y6	4	-
234	6	V7	AA1	3	-
235	6	Y2	Y3	4	-
236	6	W5	Y5	1	VREF
237	6	W6	W4	√	-
238	6	W2	V6	4	-
239	6	V4	U9	1	-
240	6	T8	AB2	√	VREF
241	6	W1	U5	√	-
242	6	T9	Y1	2	-
243	6	U3	T7	4	-
244	6	V2	T5	4	VREF
245	6	T6	R9	4	-
246	6	U2	T4	4	VREF
247	7	R10	T1	NA	
248	7	R6	R5	4	-
249	7	R4	R8	4	VREF
250	7	R3	R7	4	-
251	7	P6	P10	4	VREF
252	7	P2	P5	4	-
253	7	P4	P7	2	-
254	7	R2	N4	√	-
255	7	P1	N7	√	VREF

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
4	IO_L212N_YY	AP18
4	IO_L213P_Y	AF18
4	IO_L213N_Y	AP17
4	IO_VREF_L214P_Y	AJ18[1]
4	IO_L214N_Y	AL18
4	IO_LVDS_DLL_L215P	AM18
5	GCK1	AL19
5	IO	AF17[3]
5	IO	AG12[3]
5	IO	AH12
5	IO	AJ10[3]
5	IO	AJ11[3]
5	IO	AK7[3]
5	IO	AK13[3]
5	IO	AL13[3]
5	IO	AM4[3]
5	IO	AN9
5	IO	AN10[3]
5	IO	AN16
5	IO	AN17[3]
5	IO_LVDS_DLL_L215N	AL17
5	IO_L216P_Y	AH17
5	IO_VREF_L216N_Y	AM17[1]
5	IO_L217P_Y	AJ17
5	IO_L217N_Y	AG17
5	IO_L218P_YY	AP16
5	IO_VREF_L218N_YY	AL16
5	IO_L219P_YY	AJ16
5	IO_L219N_YY	AM16
5	IO_L220P	AK16[5]
5	IO_L220N	AP15[4]
5	IO_L221P_Y	AL15
5	IO_L221N_Y	AH16

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
5	IO_L222P_Y	AN15
5	IO_L222N_Y	AF16
5	IO_L223P_Y	AP14[5]
5	IO_L223N_Y	AE16[4]
5	IO_L224P_YY	AK15
5	IO_VREF_L224N_YY	AJ15
5	IO_L225P_YY	AH15
5	IO_L225N_YY	AN14
5	IO_L226P	AK14[5]
5	IO_L226N	AG15[4]
5	IO_L227P_Y	AM13
5	IO_L227N_Y	AF15
5	IO_L228P_Y	AG14
5	IO_L228N_Y	AP13
5	IO_L229P_YY	AE14[5]
5	IO_L229N_YY	AE15[4]
5	IO_L230P_YY	AN13
5	IO_VREF_L230N_YY	AG13
5	IO_L231P_YY	AH14
5	IO_L231N_YY	AP12
5	IO_L232P_Y	AJ14
5	IO_L232N_Y	AL14
5	IO_L233P_Y	AF13
5	IO_L233N_Y	AN12
5	IO_L234P_Y	AF14
5	IO_L234N_Y	AP11
5	IO_L235P_Y	AN11
5	IO_L235N_Y	AH13
5	IO_L236P_YY	AM12
5	IO_L236N_YY	AL12
5	IO_L237P_YY	AJ13
5	IO_VREF_L237N_YY	AP10
5	IO_L238P_Y	AK12
5	IO_L238N_Y	AM10

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
NA	GND	AP2
NA	GND	AN3
NA	GND	AM20
NA	GND	AK30
NA	GND	AG8
NA	GND	AC29
NA	GND	Y3
NA	GND	Y32
NA	GND	W21
NA	GND	V21
NA	GND	T8
NA	GND	T27
NA	GND	R21
NA	GND	P21
NA	GND	H19
NA	GND	F29
NA	GND	C11
NA	GND	B3
NA	GND	A32
NA	GND	AP3
NA	GND	AN32
NA	GND	AM24
NA	GND	AJ6
NA	GND	AG16
NA	GND	AA14
NA	GND	Y14
NA	GND	W8
NA	GND	W27
NA	GND	U14
NA	GND	T14
NA	GND	R3
NA	GND	R32
NA	GND	M6
NA	GND	H27

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
NA	GND	E5
NA	GND	C15
NA	GND	B32
NA	GND	A33
NA	GND	AP7
NA	GND	AN33
NA	GND	AM32
NA	GND	AJ12
NA	GND	AG19
NA	GND	AA15
NA	GND	Y15
NA	GND	W14
NA	GND	V14
NA	GND	U15
NA	GND	T15
NA	GND	R14
NA	GND	P14
NA	GND	M29
NA	GND	G1
NA	GND	E18
NA	GND	C20
NA	GND	B33
NA	GND	A34
NA	GND	AP28
NA	GND	AN34
NA	GND	AM33
NA	GND	AJ23
NA	GND	AG27
NA	GND	AA16
NA	GND	Y16
NA	GND	W15
NA	GND	V15
NA	GND	U16
NA	GND	T16